2SC3937

Silicon NPN epitaxial planar type

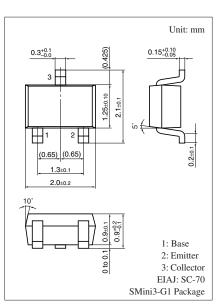
For UHF band low-noise amplification

Features

- Low noise figure NF
- High forward transfer gain $|S_{21e}|^2$
- \bullet High transition frequency $f_{\rm T}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

ADSolute Maximum hatings $T_a = 25$ C								
Parameter	Symbol	Rating	Unit					
Collector-base voltage (Emitter open)	V _{CBO}	15	V					
Collector-emitter voltage (Base open)	V _{CEO}	10	V					
Emitter-base voltage (Collector open)	V _{EBO}	2	V					
Collector current	I _C	80	mA					
Collector power dissipation	P _C	150	mW					
Junction temperature	Tj	150	°C					
Storage temperature	T _{stg}	-55 to +150	°C					
	5		e					

Absolute Maximum Ratings $T_a = 25^{\circ}C$



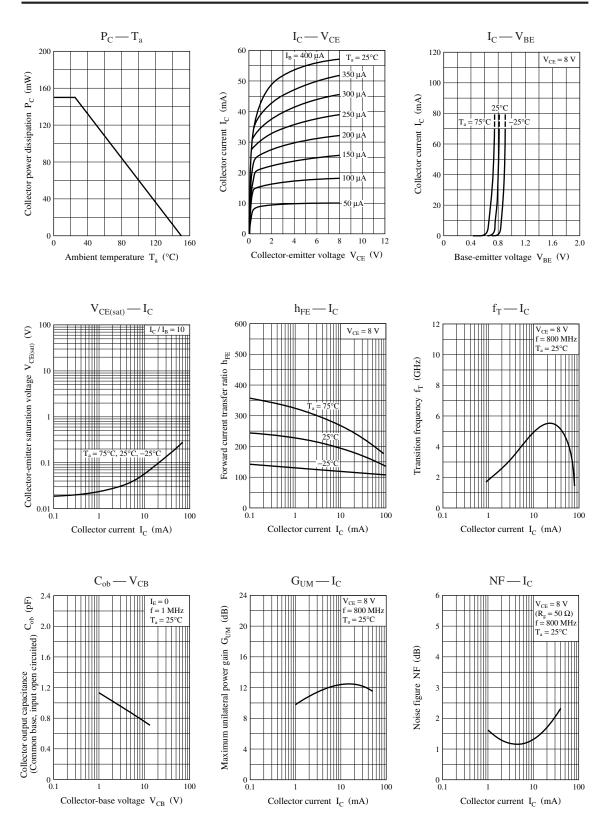
Marking Symbol: 2W

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 15 \text{ V}, I_E = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 1 V, I_C = 0$			1	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 8 V, I_C = 20 mA$	50		300	_
	h _{FE2}	$V_{CE} = 1 V, I_C = 3 mA$	80		280	
Transition frequency	f _T	$V_{CE} = 8 \text{ V}, I_C = 20 \text{ mA}, f = 0.8 \text{ GHz}$		6		GHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.7	1.2	pF
(Common base, input open circuited)						
Forward transfer gain	$ S_{21e} ^2$	$V_{CE} = 8 V, I_C = 20 mA, f = 0.8 GHz$		13		dB
Maximum unilateral power gain	G _{UM}	$V_{CE} = 8 V, I_C = 20 mA, f = 0.8 GHz$		14		dB
Noise figure	NF	$V_{CE} = 8 V, I_C = 7 mA, f = 0.8 GHz$		1.0	1.7	dB

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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